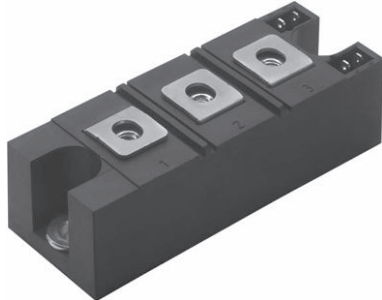


## “Half-Bridge” IGBT INT-A-PAK, (Standard Speed IGBT), 100 A


**INT-A-PAK**

PRODUCT SUMMARY	
$V_{CES}$	600 V
$I_C$ DC	220 A
$V_{CE(on)}$ at 100 A, 25 °C	1.11 V
Speed	DC to 1 kHz
Package	INT-A-PAK
Circuit	Half bridge

### FEATURES

- Standard speed PT IGBT technology
- Optimized for hard switching speed
- FRED Pt® antiparallel diodes with fast recovery
- Very low conduction losses
- $Al_2O_3$  DBC
- UL approved file E78996
- Designed for industrial level
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS  
COMPLIANT**

### BENEFITS

- Optimized for high current inverter stages (AC TIG welding machines)
- Direct mounting to heatsink
- Very low junction to case thermal resistance
- Low EMI

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	MAX.	UNITS
Collector to emitter voltage	$V_{CES}$		600	V
Continuous collector current	$I_C$	$T_C = 25\text{ °C}$	220	A
		$T_C = 130\text{ °C}$	100	
Pulsed collector current	$I_{CM}$		440	
Peak switching current	$I_{LM}$		440	
Gate to emitter voltage	$V_{GE}$		± 20	V
RMS isolation voltage	$V_{ISOL}$	Any terminal to case, $t = 1\text{ min}$	2500	
Maximum power dissipation	$P_D$	$T_C = 25\text{ °C}$	780	W
		$T_C = 100\text{ °C}$	312	
Operating junction temperature range	$T_J$		-40 to +150	°C
Storage temperature range	$T_{Stg}$		-40 to +125	

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Collector to emitter breakdown voltage	$V_{BR(CES)}$	$V_{GE} = 0\text{ V}, I_C = 1\text{ mA}$	600	-	-	V
Collector to emitter voltage	$V_{CE(on)}$	$V_{GE} = 15\text{ V}, I_C = 100\text{ A}$	-	1.11	1.28	
		$I_C = 200\text{ A}$	-	1.39	-	
		$V_{GE} = 15\text{ V}, I_C = 100\text{ A}, T_J = 125\text{ °C}$	-	1.08	1.22	
Gate threshold voltage	$V_{GE(th)}$	$I_C = 0.25\text{ mA}$	3	-	6	
Collector to emitter leakage current	$I_{CES}$	$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}$	-	-	1	mA
		$V_{GE} = 0\text{ V}, V_{CE} = 600\text{ V}, T_J = 125\text{ °C}$	-	-	10	
Diode forward voltage drop	$V_{FM}$	$I_C = 100\text{ A}, V_{GE} = 0\text{ V}$	-	1.44	1.96	V
		$I_C = 100\text{ A}, V_{GE} = 0\text{ V}, T_J = 125\text{ °C}$	-	1.25	1.54	
Gate to emitter leakage current	$I_{GES}$	$V_{GE} = \pm 20\text{ V}$	-	-	± 250	nA



SWITCHING CHARACTERISTICS (T <sub>J</sub> = 25 °C unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Total gate charge	Q <sub>g</sub>	I <sub>C</sub> = 100 A V <sub>CC</sub> = 400 V V <sub>GE</sub> = 15 V	-	640	700	nC
Gate to emitter charge	Q <sub>ge</sub>		-	108	120	
Gate to collector charge	Q <sub>gc</sub>		-	230	300	
Rise time	t <sub>r</sub>	I <sub>C</sub> = 100 A V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V R <sub>g</sub> = 15 Ω T <sub>J</sub> = 25 °C	-	0.45	-	μs
Fall time	t <sub>f</sub>		-	1.0	-	
Turn-on switching energy	E <sub>on</sub>		-	4	6	
Turn-off switching energy	E <sub>off</sub>	I <sub>C</sub> = 100 A, V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V, R <sub>g</sub> = 15 Ω T <sub>J</sub> = 125 °C	-	23	29	mJ
Total switching energy	E <sub>ts</sub>		-	27	35	
Turn-on switching energy	E <sub>on</sub>		-	6	12	
Turn-off switching energy	E <sub>off</sub>	I <sub>C</sub> = 100 A, V <sub>CC</sub> = 480 V V <sub>GE</sub> = 15 V, R <sub>g</sub> = 15 Ω T <sub>J</sub> = 125 °C	-	35	40	mJ
Total switching energy	E <sub>ts</sub>		-	41	52	
Turn-on switching energy	E <sub>on</sub>		-	6	12	
Input capacitance	C <sub>ies</sub>	V <sub>GE</sub> = 0 V V <sub>CC</sub> = 30 V f = 1.0 MHz	-	16 250	-	pF
Output capacitance	C <sub>oes</sub>		-	1040	-	
Reverse transfer capacitance	C <sub>res</sub>		-	190	-	
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A dI <sub>F</sub> /dt = 200 A/μs V <sub>rr</sub> = 200 V	-	91	155	ns
Diode peak reverse current	I <sub>rr</sub>		-	10.6	15	A
Diode recovery charge	Q <sub>rr</sub>		-	500	900	nC
Diode reverse recovery time	t <sub>rr</sub>	I <sub>F</sub> = 50 A dI <sub>F</sub> /dt = 200 A/μs V <sub>rr</sub> = 200 V, T <sub>J</sub> = 125 °C	-	180	344	ns
Diode peak reverse current	I <sub>rr</sub>		-	17	20.5	A
Diode recovery charge	Q <sub>rr</sub>		-	1633	2315	nC

THERMAL AND MECHANICAL SPECIFICATIONS						
PARAMETER	SYMBOL	MIN.	TYP.	MAX.	UNITS	
Operating junction temperature range	T <sub>J</sub>	-40	-	150	°C	
Storage temperature range	T <sub>Stg</sub>	-40	-	125		
Junction to case	per switch	R <sub>thJC</sub>	-	-	0.16	°C/W
	per diode		-	-	0.48	
Case to sink per module	R <sub>thCS</sub>	-	0.1	-		
Mounting torque	case to heatsink	-	-	4	Nm	
	case to terminal 1, 2, 3	-	-	3		
Weight		-	185	-	g	

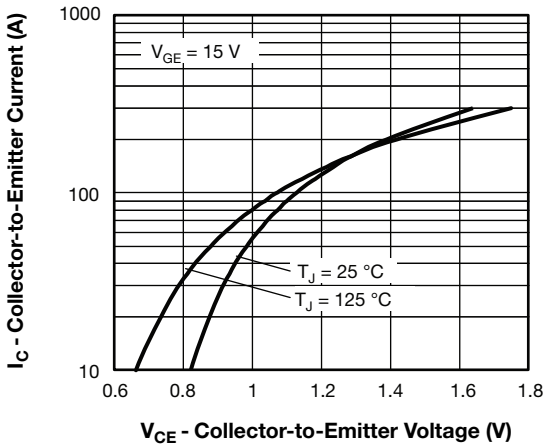


Fig. 1 - Typical Output Characteristics

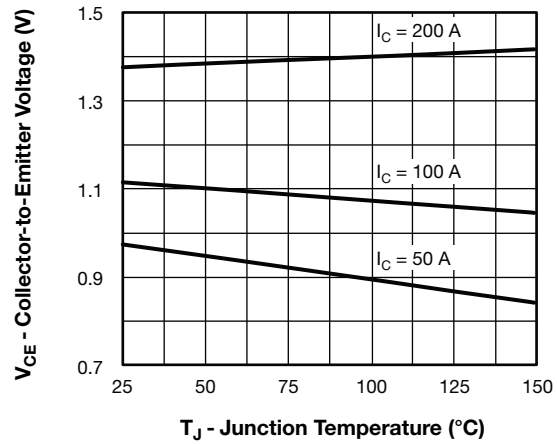


Fig. 4 - Typical Collector to Emitter Voltage vs. Junction Temperature

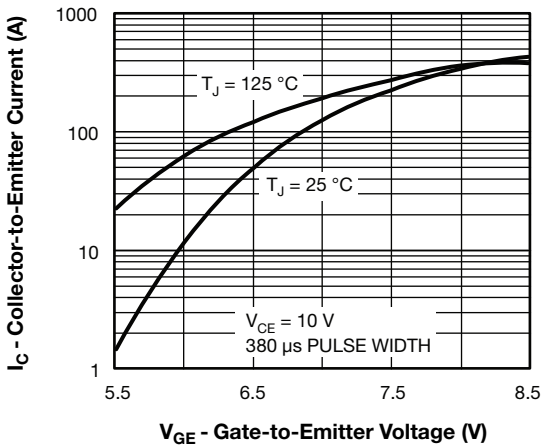


Fig. 2 - Typical Transfer Characteristics

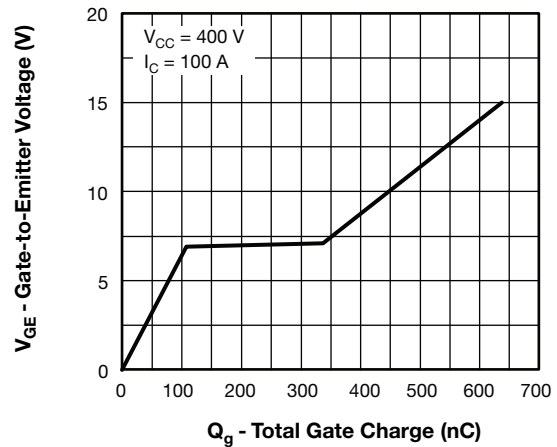


Fig. 5 - Typical Gate Charge vs. Gate to Emitter Voltage

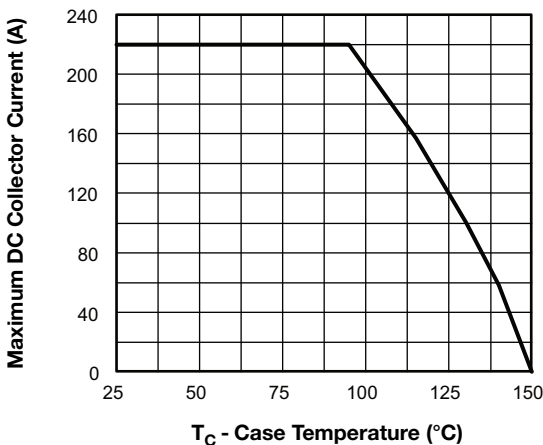


Fig. 3 - Maximum Collector Current vs. Case Temperature

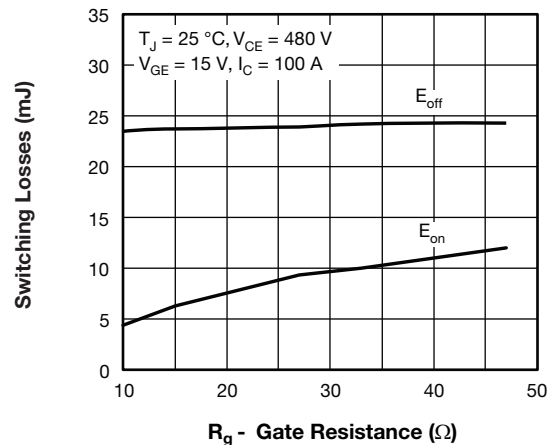


Fig. 6 - Typical Switching Losses vs. Gate Resistance

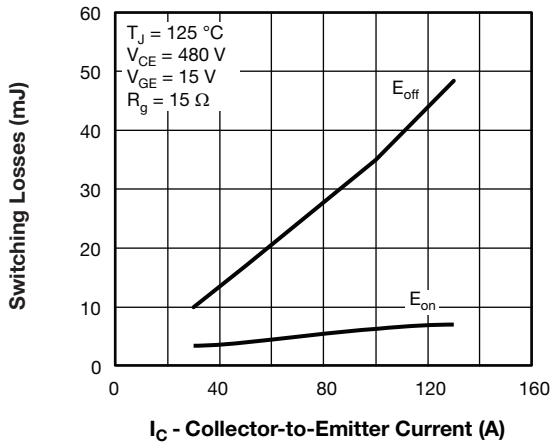


Fig. 7 - Typical Switching Losses vs. Collector to Emitter Current

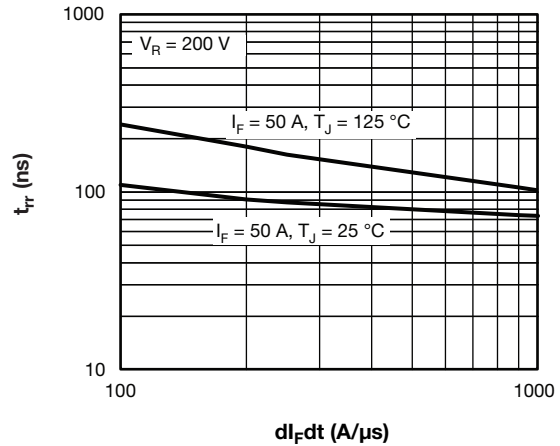


Fig. 9 - Typical Reverse Recovery Time vs.  $dI_F/dt$

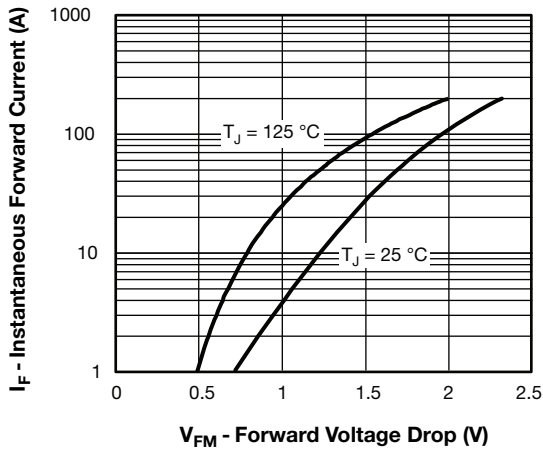


Fig. 8 - Maximum Forward Voltage Drop vs. Instantaneous Forward Current

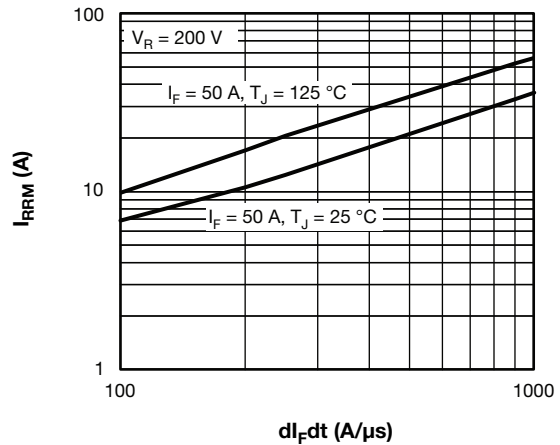


Fig. 10 - Typical Reverse Recovery Current vs.  $dI_F/dt$

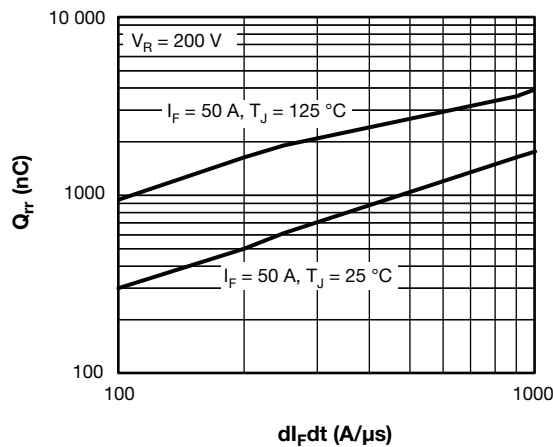
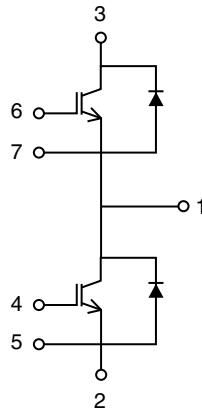


Fig. 11 - Typical Stored Charge vs.  $dI_F/dt$

**ORDERING INFORMATION TABLE**

Device code	<b>VS-</b>	<b>GA</b>	<b>100</b>	<b>T</b>	<b>S</b>	<b>60</b>	<b>S</b>	<b>F</b>	<b>PbF</b>
	①	②	③	④	⑤	⑥	⑦	⑧	⑨

- 1** - Vishay Semiconductors product
- 2** - Essential part number IGBT modules
- 3** - Current rating (100 = 100 A)
- 4** - Circuit configuration (T = Half bridge)
- 5** - INT-A-PAK
- 6** - Voltage code (60 = 600 V)
- 7** - Speed/type (S = Standard speed IGBT)
- 8** - Diode type
- 9** - None = Standard production; PbF = Lead (Pb)-free

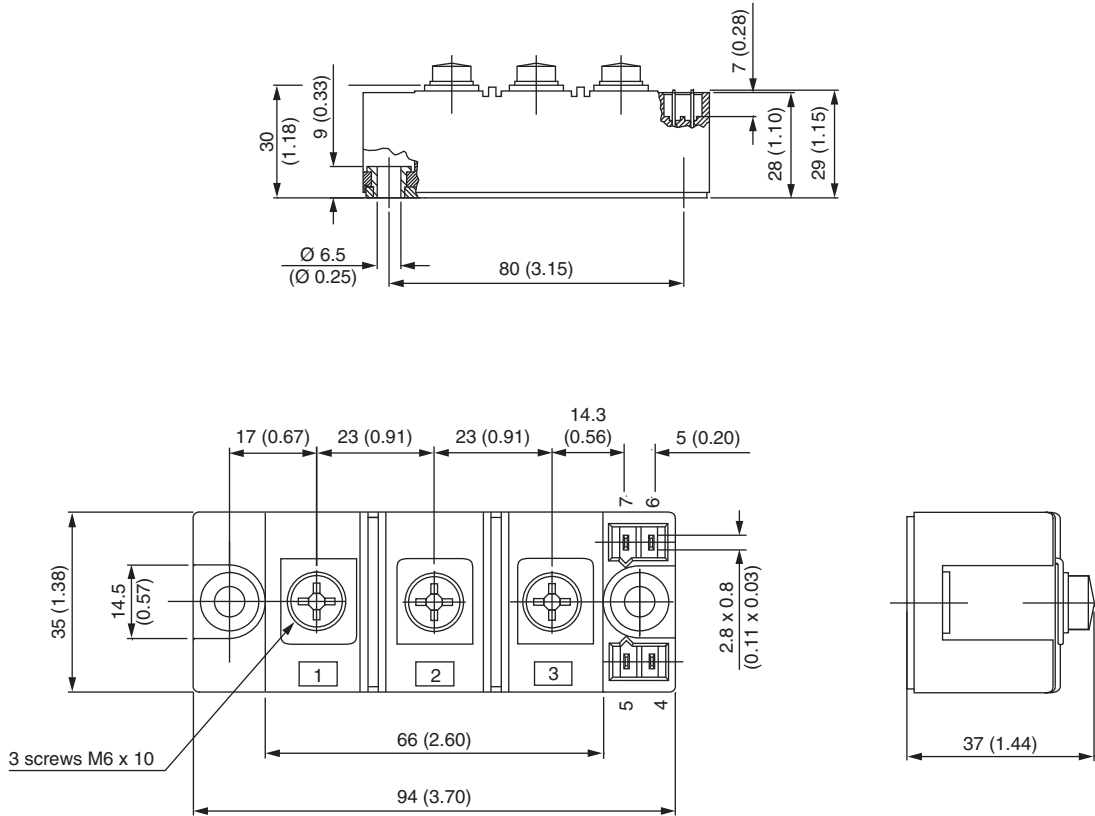
**CIRCUIT CONFIGURATION**

**LINKS TO RELATED DOCUMENTS**

Dimensions	<a href="http://www.vishay.com/doc?95173">www.vishay.com/doc?95173</a>
------------	--



## INT-A-PAK IGBT

**DIMENSIONS** in millimeters (inches)





## Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and/or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

## Material Category Policy

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as RoHS-Compliant fulfill the definitions and restrictions defined under Directive 2011/65/EU of The European Parliament and of the Council of June 8, 2011 on the restriction of the use of certain hazardous substances in electrical and electronic equipment (EEE) - recast, unless otherwise specified as non-compliant.**

**Please note that some Vishay documentation may still make reference to RoHS Directive 2002/95/EC. We confirm that all the products identified as being compliant to Directive 2002/95/EC conform to Directive 2011/65/EU.**

**Vishay Intertechnology, Inc. hereby certifies that all its products that are identified as Halogen-Free follow Halogen-Free requirements as per JEDEC JS709A standards. Please note that some Vishay documentation may still make reference to the IEC 61249-2-21 definition. We confirm that all the products identified as being compliant to IEC 61249-2-21 conform to JEDEC JS709A standards.**